



TH501 Copper

DESCRIPTION

The TH501 is a pure copper wire possessing excellent conductivity. It produces dense, well-bonded coatings with excellent machine-ability. It is widely used for electrical conductivity and architectural coatings to just name a few uses.

TYPICAL DEPOSIT CHARACTERISTICS:

- Bond Strength 7000 psi
- Typical Hardness HRB 67
- Deposit Rate 18 lbs./hr./150-200 Amps
- Deposit Efficiency 80%
- Wire Coverage 2 sq. ft./lbs. @ 12 mils
- Surface Texture Variable
- Machinability Good

SURFACE PREPARATION:

Surface should be clean, white metal, with no oxides (rust), dirt, grease, or oil on the surface to be coated. NOTE: It is best not to handle surfaces after cleaning. Recommended method of preparation is, to grit blast with 24 mesh aluminum oxide, rough grind, or rough machine in a lathe. *Thermion recommends a 3.5 mil minimum anchor tooth profile.

Applications:

- Electrical Conductivity surfaces
- Decorative Purposes
- Carbon Brushes
- Discharge Electrodes
- Railway Carriage Axles
- EMI Protection

NOMINAL CHEMICAL COMPOSITION (wt. %):

Cu
98.5

RECOMMENDED SPRAY PARAMETERS:

Diameter	Air Pressure	Voltage	Amperage	Standoff
1/16" (1.6mm)	80-100 psi	28-32	100-300	4-7" (10-17cm)

Parameters are typical and may vary depending on equipment used.

STANDARD SIZES & PACKAGING:

Diameter	Packaging
1/16 (1.6mm)	33#
3/32 (2.3mm)	33#